

Data sheet Product ICK PGA 17 x 17 x 8



Heatsinks and active heatsinks for processors>Heatsinks for PGA

43,1 x 43,1 x 8 mm, for IC design PGA and others

Features

way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
width:	43.1 mm
height:	8 mm
plate thickness:	3 mm
length:	43.1 mm
thermal resistance:	13.2 - 3.1 K/W
dissipation loss:	5.2 W
surface:	black anodised

Technical Drawing

